

### STGW39NC60VD

N-channel 40A - 600V - TO-247 Very fast switching PowerMESH™ IGBT

#### **Features**

Туре	V <sub>CES</sub>	V <sub>CE(sat)</sub> (Max)@ 25°C	I <sub>C</sub> @100°C
STGW39NC60VD	600V	<2.5V	40A

- Low C<sub>RES</sub> / C<sub>IES</sub> ratio (no cross conduction susceptibility)
- High frequency operation
- Very soft ultra fast recovery anti parallel diode

### **Applications**

- High frequency inverters
- UPS
- Motor drivers

Induction heating

### **Description**

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH<sup>™</sup> IGBTs, with outstanding performances. The suffix "V" identifies a family optimized for high frequency.

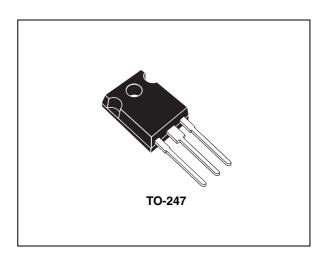


Figure 1. Internal schematic diagram

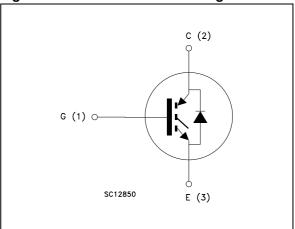


Table 1. Device summary

Order code	Marking	Package	Packaging
STGW39NC60VD	GW39NC60VD	TO-247	Tube

Contents STGW39NC60VD

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STGW39NC60VD Electrical ratings

# 1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-emitter voltage (V <sub>GS</sub> = 0)	600	V
I <sub>C</sub> <sup>(1)</sup>	Collector current (continuous) at 25°C	70	Α
I <sub>C</sub> <sup>(1)</sup>	Collector current (continuous) at 100°C	40	Α
I <sub>CL</sub> <sup>(2)</sup>	Turn-off SOA minimum current	220	Α
V <sub>GE</sub>	Gate-emitter voltage	± 20	V
IF	Diode RMS forward current at Tc=25°C	30	Α
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25°C	250	W
T <sub>j</sub>	Operating junction temperature	- 55 to 150	°C

<sup>1.</sup> Calculated according to the iterative formula:

$$I_{C}(T_{C}) = \frac{T_{JMAX}^{-T}C}{R_{THJ-C}^{\times V}CESAT(MAX)^{(T}C, \ ^{I}C)}$$

2. Vclamp = 480V , Tj = 150°C, R\_G = 10 $\Omega$ , V<sub>GE</sub>= 15V

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case max (IGBT)	0.5	°C/W
R <sub>thj-case</sub>	Thermal resistance junction-case max (diode)	1.5	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient max	50	°C/W

Electrical characteristics STGW39NC60VD

## 2 Electrical characteristics

( $T_{CASE}$ =25°C unless otherwise specified)

Table 4. Static

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>BR(CES)</sub>	Collector-emitter breakdown voltage	I <sub>C</sub> = 1mA, V <sub>GE</sub> = 0	600			V
V <sub>CE(SAT)</sub>	Collector-emitter saturation voltage	V <sub>GE</sub> =15V, I <sub>C</sub> =30A,Tj=25°C V <sub>GE</sub> =15V, I <sub>C</sub> =30A,Tj=125°C		1.8 1.7	2.5	V V
V <sub>GE(th)</sub>	Gate threshold voltage	$V_{CE} = V_{GE}$ , $I_{C} = 250\mu A$	3.75		5.75	٧
I <sub>CES</sub>	Collector-emitter leakage current (V <sub>GE</sub> = 0)	V <sub>CE</sub> = Max rating,Tc=25°C V <sub>CE</sub> = Max rating, Tc=125°C			500 5	μA mA
I <sub>GES</sub>	Gate-emitter leakage current (V <sub>CE</sub> = 0)	V <sub>GE</sub> = ± 20V , V <sub>CE</sub> = 0			±100	nA
9 <sub>fs</sub>	Forward transconductance	$V_{CE} = 15V_{,} I_{C} = 30A$		20		S

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max	Unit
C <sub>ies</sub> C <sub>oes</sub> C <sub>res</sub>	Input capacitance Output capacitance Reverse transfer capacitance	$V_{CE} = 25V$ , f = 1 MHz, $V_{GE} = 0$		2900 298 59		pF pF pF
Q <sub>g</sub> Q <sub>ge</sub> Q <sub>gc</sub>	Total gate charge Gate-emitter charge Gate-collector charge	$V_{CE} = 390V$ , $I_{C} = 30A$ , $V_{GE} = 15V$ , (see Figure 19)		126 16 46		nC nC nC

Table 6. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>onf</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC}$ =390 V, $I_{C}$ = 30A, $R_{G}$ =10 $\Omega$ , $V_{GE}$ =15V $T_{j}$ =25°C (see Figure 18)		33 13 2500		ns ns A/µs
t <sub>d(on)</sub> t <sub>r</sub> (di/dt) <sub>on</sub>	Turn-on delay time Current rise time Turn-on current slope	$V_{CC}$ =390 V, $I_{C}$ = 30A, $R_{G}$ =10 $\Omega$ , $V_{GE}$ =15V $T_{J}$ =125°C (see Figure 18)		32 14 2280		ns ns A/µs
t <sub>r(Voff)</sub> t <sub>d(off)</sub> t <sub>f</sub>	Off voltage rise time Turn-off delay time Current fall time	$V_{CC}$ =390 V, $I_{C}$ = 30A, $R_{G}$ =10 $\Omega$ , $V_{GE}$ =15V $T_{J}$ =25°C (see Figure 18)		33 178 65		ns ns ns
$t_{\text{r(Voff)}} \\ t_{\text{d(off)}} \\ t_{\text{f}}$	Off voltage rise time Turn-off delay time Current fall time	$V_{CC}$ =390 V, $I_{C}$ = 30A, $R_{G}$ =10 $\Omega$ , $V_{GE}$ =15V Tj=125°C <i>(see Figure 18)</i>		68 238 128		ns ns ns

Table 7. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
E <sub>on</sub> (1)	Turn-on switching losses	$V_{CC} = 390V, I_{C} = 30A$		333		μJ
E <sub>off</sub> <sup>(2)</sup>	Turn-off switching losses	$R_{G}$ = 10 $\Omega$ , $V_{GE}$ = 15 $V$ ,		537		μJ
E <sub>ts</sub>	Total switching losses	Tj= 25°C (see Figure 20)		870		μJ
E <sub>on</sub> (1)	Turn-on switching losses	$V_{CC} = 390V, I_{C} = 30A$		618		μJ
E <sub>off</sub> (2)	Turn-off switching losses	$R_G = 10\Omega$ , $V_{GE} = 15V$ ,		1125		μJ
E <sub>ts</sub>	Total switching losses	Tj= 125°C (see Figure 20)		1743		μJ

Eon is the turn-on losses when a typical diode is used in the test circuit in figure 2 Eon include diode recovery energy. If the IGBT is offered in a package with a co-pak diode, the co-pack diode is used as external diode. IGBTs & Diode are at the same temperature (25°C and 125°C)

Table 8. Collector-emitter diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
V <sub>f</sub>	Forward on-voltage	If = 15A If = 15A, Tj = 125°C If = 30A, Tj = 125°C		1.3 1.1 1.2	2.9	V V V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>rrm</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	If = 30A, $V_R$ = 50V, $T_j$ = 25°C, di/dt =100A/ $\mu$ s (see Figure 21)		45 56 2.55		ns nC A
t <sub>rr</sub> Q <sub>rr</sub> I <sub>rrm</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	If = 30A, $V_R$ = 50V, $T_j$ = 125°C,di/dt =100A/ $\mu$ s (see Figure 21)		100 290 5.8		ns nC A

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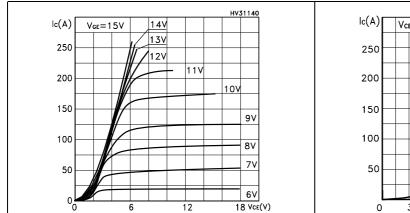
<sup>2.</sup> Turn-off losses include also the tail of the collector current

Electrical characteristics STGW39NC60VD

### 2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

Figure 3. Transfer characteristics



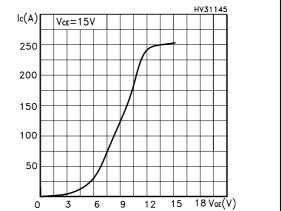
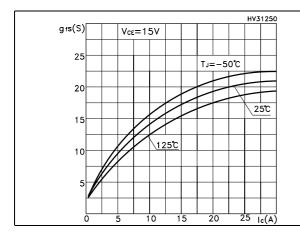


Figure 4. Transconductance

Figure 5. Collector-emitter on voltage vs temperature



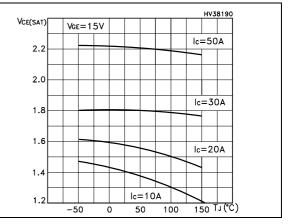
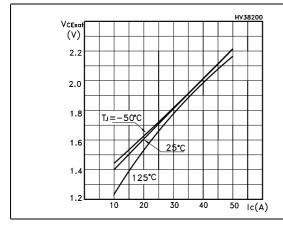
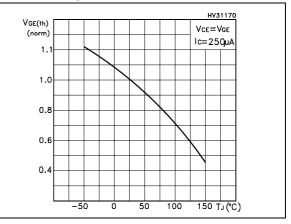


Figure 6. Collector-emitter on voltage vs collector current

Figure 7. Normalized gate threshold vs temperature





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Figure 8. Normalized breakdown voltage vs Figure 9. Gate charge vs gate-emitter voltage temperature

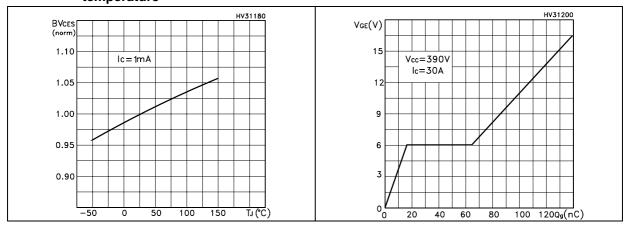


Figure 10. Capacitance variations

Figure 11. Switching losses vs temperature

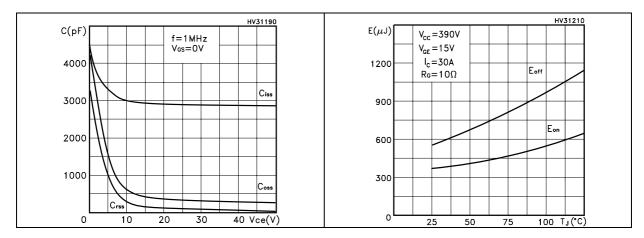
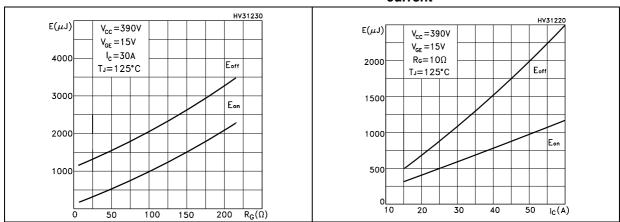


Figure 12. Switching losses vs gate resistance Figure 13. Switching losses vs collector current

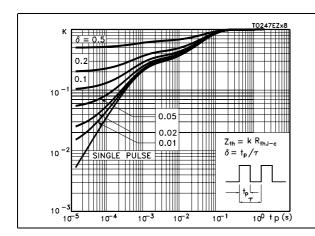


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Electrical characteristics STGW39NC60VD

Figure 14. Thermal impedance

Figure 15. Turn-off SOA



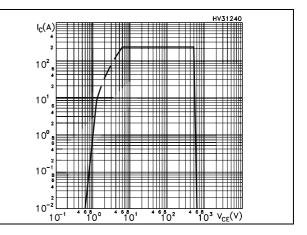
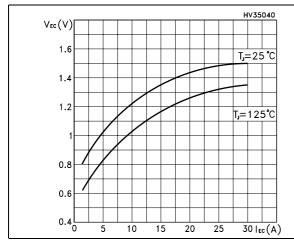
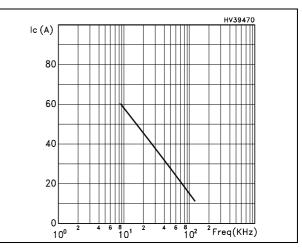


Figure 16. Emitter-collector diode characteristics

Figure 17. I<sub>C</sub> vs. frequency





### 2.2 Frequency applications

For a fast IGBT suitable for high frequency applications, the typical collector current vs. maximum operating frequency curve is reported. That frequency is defined as follows:

$$f_{MAX} = (P_D - P_C) / (E_{ON} + E_{OFF})$$

• The maximum power dissipation is limited by maximum junction to case thermal resistance:

#### **Equation 1**

$$P_D = \Delta T / R_{THJ-C}$$

considering 
$$\Delta T = T_J - T_C = 125 \,^{\circ}\text{C} - 75 \,^{\circ}\text{C} = 50 \,^{\circ}\text{C}$$

The conduction losses are:

#### **Equation 2**

$$P_C = I_C * V_{CE(SAT)} * \delta$$

with 50% of duty cycle, V<sub>CESAT</sub> typical value @125°C.

Power dissipation during ON & OFF commutations is due to the switching frequency:

#### **Equation 3**

$$P_{SW} = (E_{ON} + E_{OFF}) * freq.$$

Typical values @ 125°C for switching losses are used (test conditions: V<sub>CE</sub> = 390V, V<sub>GE</sub> = 15V, R<sub>G</sub> = 10 Ohm). Furthermore, diode recovery energy is included in the E<sub>ON</sub> (see note 2), while the tail of the collector current is included in the E<sub>OFF</sub> measurements (see note 3).

Test circuit STGW39NC60VD

## 3 Test circuit

Figure 18. Test circuit for inductive load switching

Figure 19. Gate charge test circuit

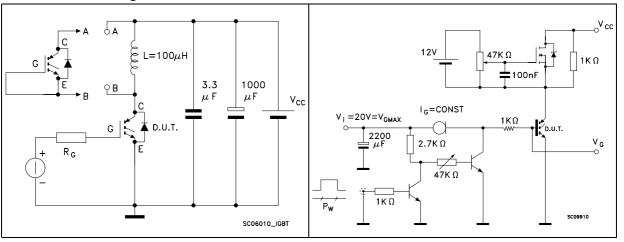
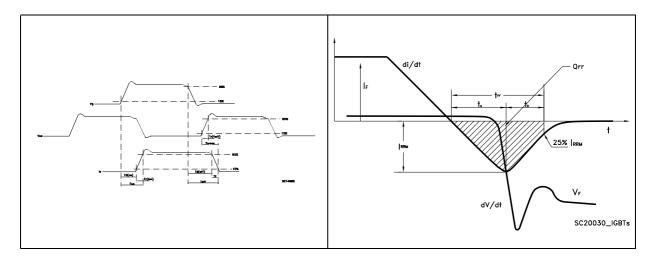


Figure 20. Switching waveforms

Figure 21. Diode recovery times waveform



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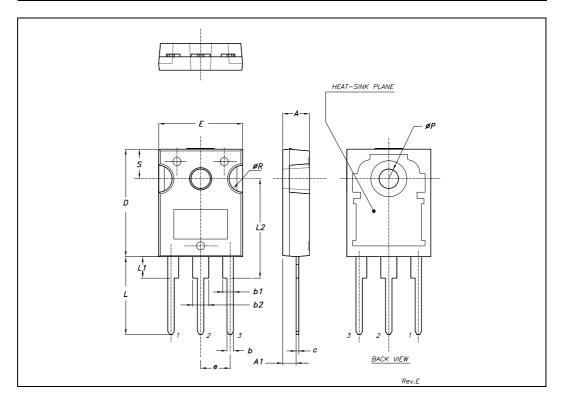
## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: <a href="https://www.st.com">www.st.com</a>

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### **TO-247 MECHANICAL DATA**

DIM	mm.		inch			
DIM.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
Α	4.85		5.15	0.19		0.20
A1	2.20		2.60	0.086		0.102
b	1.0		1.40	0.039		0.055
b1	2.0		2.40	0.079		0.094
b2	3.0		3.40	0.118		0.134
С	0.40		0.80	0.015		0.03
D	19.85		20.15	0.781		0.793
E	15.45		15.75	0.608		0.620
е		5.45			0.214	
L	14.20		14.80	0.560		0.582
L1	3.70		4.30	0.14		0.17
L2		18.50			0.728	
øΡ	3.55		3.65	0.140		0.143
øR	4.50		5.50	0.177		0.216
S		5.50			0.216	



STGW39NC60VD Revision history

# 5 Revision history

Table 9. Document revision history

Date	Revision Changes	
17-Nov-2005 1		First release
05-May-2006	2	Inserted curves
10-Jul-2006	3	Modified value on Absolute maximum ratings
01-Dec-2006	4	Modified value on <i>Dynamic</i>
16-May-2007	5	New curves updated: Figure 5 and Figure 6
22-Aug-2007 6		Added new Figure 17 and new section 2.2: Frequency applications

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